



Product End-of-Life Disassembly Instructions

Product Category: Personal Computers

Marketing Name / Model
 [List multiple models if applicable.]

Name / Model #1: HP Compaq dx2810/dx2818 Microtower Business PC

Name / Model #2

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm	2 (1 sys bd, 1 P/S)
Batteries	All types including standard alkaline and lithium coin or button style batteries	1
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	
Cathode Ray Tubes (CRT)		
Capacitors / condensers (Containing PCB/PCT)		
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		2 (P/S board)
External electrical cables and cords		
Gas Discharge Lamps		
Plastics containing Brominated Flame Retardants		
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	
Components and waste containing asbestos		
Components, parts and materials containing refractory ceramic fibers		
Components, parts and materials containing radioactive substances		

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Description #1 Phillips screwdriver	
Description #2 Dikes	
Description #3 Torx screwdriver	T-15
Description #4 Flat head screwdriver	

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. To remove the access panel (see Figure 1):
 - a. Loosen the captive thumbscrew (1) that secures the access panel to the computer chassis.
 - b. Slide the access panel back (2) about 1.3 cm (1/2 inch), then lift it off the unit.
2. Press outward on the three latches on the right side of the bezel (1), then rotate the right side of the bezel off the chassis (2) followed by the left side (see Figure 2).
3. Remove or cut all expansion cards, cables, and any other devices from the system board.
4. To remove the heatsink from the system board (see Figure 3):
 - a. Loosen the four captive screws that secure the heatsink to the system board.
 - b. Lift the heatsink from atop the processor and set it aside.
5. To remove the system board (see Figure 4):
 - a. Remove the 8 screws that secure the system board to the chassis.
 - b. Lift the system board and slide it toward the front of the chassis and up to remove it.

NOTE: System board appearance may vary.
6. To remove the power supply:
 - a. Remove the four Phillips screws that secure the power supply to the chassis (see Figure 6).
 - b. Press the release latch on the chassis base, and then lift up the rear of the power supply to disengage it from the chassis.
 - c. Slide the power supply toward the front of the computer, rotate toward the fan so the power supply clears the lip on the top of the chassis, and then lift the power supply out of the chassis.
7. Disassemble and remove required power supply components:
 - a. Using a Phillips screwdriver, remove the screws that secure the cover to the power supply chassis.
 - b. Using dikes, cut the plastic clamp that secures the wires to the power supply cover.
NOTE: You do not need to remove the screws from the fan guard or the power connector.
 - c. Lift the cover off the power supply.
 - d. Using dikes, cut all cables connecting the PCA to the power supply.
 - f. Remove the screws that secure the power supply PCA to the chassis.
 - g. Remove the power supply PCA from the power supply chassis.
 - h. Cut or remove the capacitors as shown in Figure 7.
8. To remove the battery:

Locate the battery and battery holder on the system board. Depending on the type of battery holder on the system board, complete the following instructions to remove the battery.

TYPE 1 BATTERY HOLDER (see Figure 8):
Lift the battery out of the holder.

TYPE 2 BATTERY HOLDER (see Figure 9):
To release the battery from its holder, squeeze the metal clamp that extends above one edge of the battery. When the battery pops up, lift it out.

TYPE 3 BATTERY HOLDER (see Figure 10):
Pull back on the clip that holds the battery in place, and then remove the battery.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

FIGURE 1: Removing the access panel



FIGURE 2: Remove the front bezel



FIGURE 3: Remove the heat sink



FIGURE 4: System board screw locations



FIGURE 5: Power supply screw locations



FIGURE 6: Power supply release tab location



FIGURE 7: Power supply capacitors to cut



FIGURE 8: Type 1 battery holder

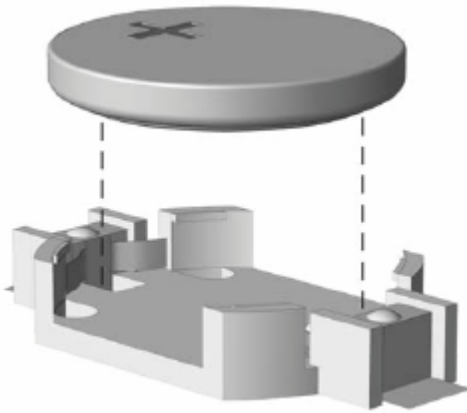


FIGURE 9: Type 2 battery holder



FIGURE 10: Type 3 battery holder

